Claim 6 (Canceled).

7. (Previously presented) The disk enclosure of claim [4, wherein the second plurality of elements includes at least one of a second temperature sensor, a second memory, and a second backplane controller.

8. (Previously presented) The disk enclosure of claim 7, wherein the second backplane controller is coupled to a second port bypass circuit, the second port bypass circuit operable to bypass a second disk drive.

Previously Presented

9. (~~Withdrawn~~) The disk enclosure of claim 5, wherein:

the first enclosure controller is coupled to a fifth bus;

the second enclosure controller is further coupled to a sixth bus;

a third switch coupled between the fifth bus and a seventh bus, the third switch operable to de-couple the fifth and the seventh buses when the voltage output from the first voltage circuit falls below the predetermined threshold; and

a fourth switch coupled between the sixth bus and the seventh bus, the fourth switch operable to de-couple the sixth and seventh buses when the voltage output from the second voltage circuit falls below the predetermined threshold.

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Previously Presented

10. (~~Withdrawn~~) The disk enclosure of claim 9, wherein the seventh bus is further coupled to a third plurality of elements.

Previously Presented

11. (~~Withdrawn~~) The disk enclosure of claim 10, wherein the third plurality of elements includes at least one of a third temperature sensor, a third memory, a third backplane controller, and an I/O expander.

Previously Presented

12. (~~Withdrawn~~) The disk enclosure of claim 11, wherein the I/O expander is coupled to at least one battery.

Previously Presented

13. (~~Withdrawn~~) The disk enclosure of claim 11, wherein the I/O expander is coupled to at least one power supply.

Claims 14 to 26 (Canceled).